



100% Material Declaration Data Sheet FGG680

PK112 (v1.2) September 22, 2006

Material Declaration Data Sheet

Average Weight: 9.648 g

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Silicon Die					0.3524	3.65%
	Silicon	7440-21-3	100.00		0.1421	
Die Attach Material					0.027	0.28%
	Silver	7440-22-4	75.00		0.020	
	Resin	Trade Secret	25.00		0.007	
Mold Compound					0.4135	4.29%
	Epoxy Resins	Trade Secret	26.00		0.106	
	SiO2	60676-86-0	74.00	Filler	0.306	
Laminate					0.7366	7.63%
	Laminate	Trade Secret	60.95		0.449	
	Solder Mask	Trade Secret	21.44		0.158	
	Copper	7440-50-8	15.47	Metal Layer	0.114	
	Nickel	7440-02-0	1.62	Metal Layer	0.012	
	Gold	7440-57-5	0.53	Metal Layer	0.004	
Heat Sink					6.4063	66.40%
	Copper	7440-50-8	97.50		6.246	
	Iron	7439-89-6	2.35		0.151	
	Phosphorus	7723-14-0	0.003		0.0002	
	Zinc	7440-66-6	0.12		0.008	
Heat Snk Plating					0.2920	3.03%
	Nickel	7440-05-0	100.00		0.2920	
Dam		Henkel FP4451			0.0130	0.13%
	Epoxy Resin	Trade Secret	100.00		0.0.130	
Bond Wire					0.0214	0.22%
	Gold	7440-57-5	100.00		0.0214	
Solder Balls					1.386	14.36%
	Tin	7440-31-5	95.50		1.32363	
	Silver	7440-22-4	4.00		0.05544	
	Copper	7440-50-8	0.50		0.00693	

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Revision History

The following table shows the revision history for this document.

Date	Revision	Revision
3/27/06	1.0	Initial release.
5/15/06	1.1	100% Material Declaration.
9/22/06	1.2	Update component descriptions.